

a series of conductive traces located on one of said top surface and said bottom surface of said base substrate,

a plurality of conductive balls connected to said series of conductive traces,

a single thin layer of material secured to said base substrate and covering said aperture such that a cavity is formed, said single thin layer of material having a thickness of from approximately 0.025 to less than approximately 0.1 mm, and a semiconductor element mounted in said cavity.

42. (twice amended) A processor system comprising:

a central processing unit; and

a memory device connected to said central processing unit, said memory device comprised of a plurality of low profile ball grid array semiconductor packages, said low profile ball grid array semiconductor packages comprised of a base substrate having a top surface and a bottom surface, said base substrate having an aperture extending from said top surface to said bottom surface,

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a series of conductive traces located on one of said top surface and said bottom surface of said base substrate,

a plurality of conductive balls connected to said series of conductive traces,

a single thin layer of material secured to said top surface of said base substrate and covering said aperture to form a downward facing cavity, said single thin layer of material having a thickness of from approximately 0.025 to less than approximately 0.1 mm, and a semiconductor element mounted in said downward facing cavity.

45. (Amended) A processor system comprising:

a central processing unit; and

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a memory device connected to said central processing unit, said memory device comprised of a plurality of low profile ball grid array semiconductor packages, said low profile ball grid array semiconductor packages comprised of a base substrate having a top surface and a bottom surface, with an aperture therein which extends from said top surface to said bottom surface,

a series of conductive traces located on one of said top surface and said bottom surface of said base substrate,

a plurality of conductive balls connected to said series of conductive traces,

a thin sheet material secured to said base substrate and covering said aperture such that a cavity is formed, said thin sheet material having a thickness of from approximately 0.025 to less than approximately 0.1 mm, and a semiconductor element mounted in said cavity.
